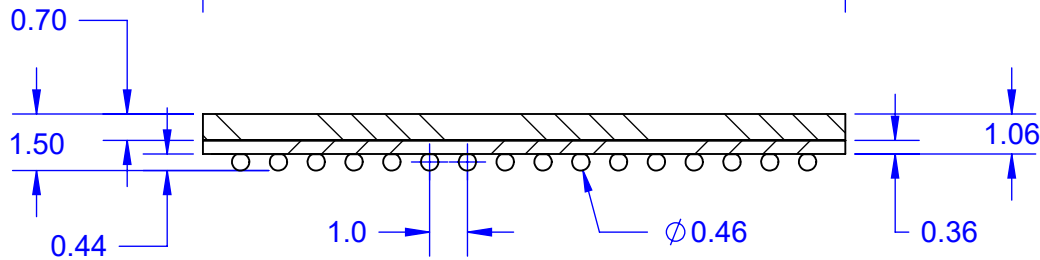
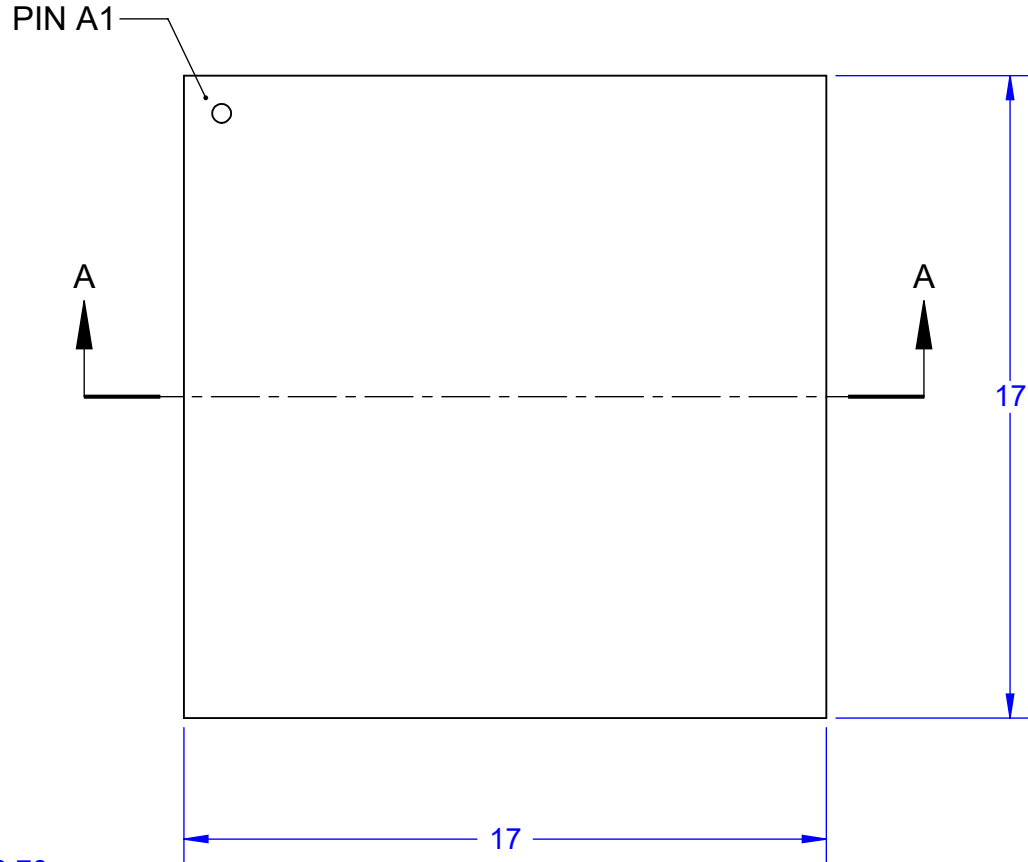
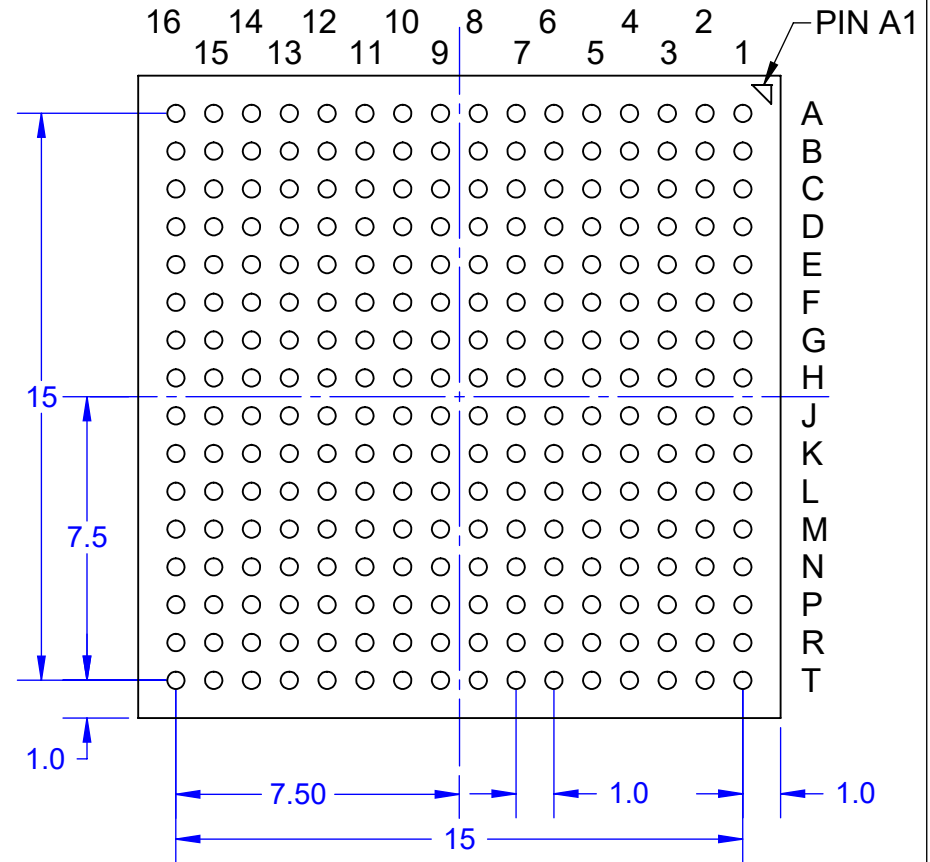


# TOP VIEW



# SECTION A-A

# BALL VIEW



Notes: (Unless Otherwise Specified).

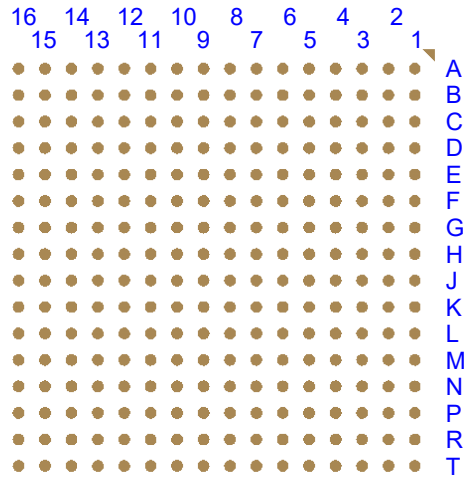
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.46mm (18 MIL).
- 4) SOLDER MASK DEFINED PAD OPENING: 0.40mm (15.7 MIL).
- 5) PAD Cu DIAMETER: 0.46mm (18 MIL).
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE: NONE.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

## PART NUMBER TABLE

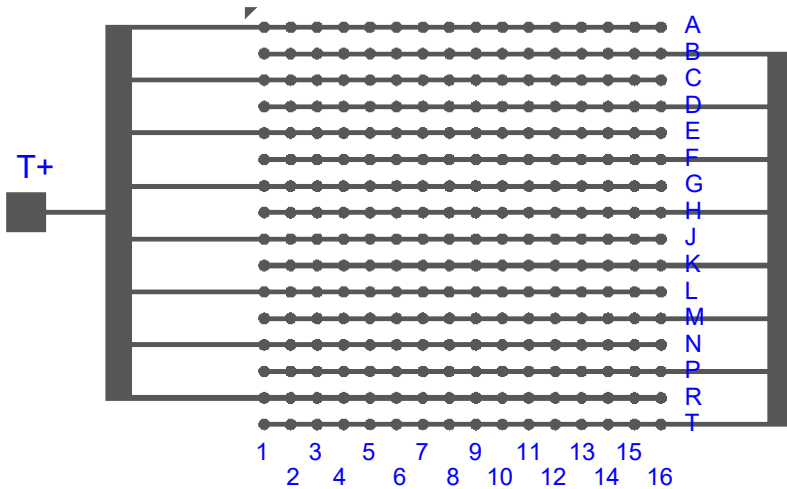
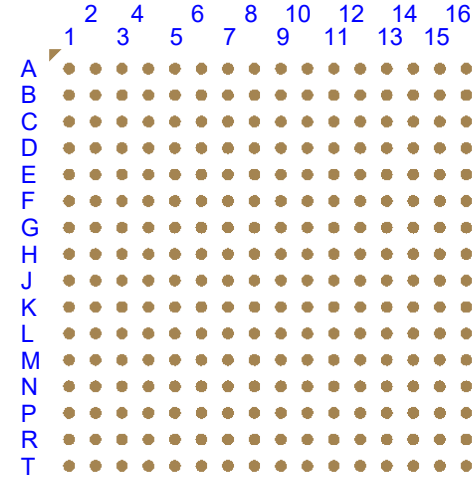
| PART NUMBER     | BALL ALLOY         | BALL CODE | RoHS | Si DIE |
|-----------------|--------------------|-----------|------|--------|
| BGA256T1.0C-ISO | Sn96.5/Ag3.0/Cu0.5 | SAC35     | YES  | NO     |
| BGA256T1.0-ISO  | Sn63/Pb37          | Sn63      | NO   | NO     |

|             |           |                                      |        |                    |              |
|-------------|-----------|--------------------------------------|--------|--------------------|--------------|
| APPROVALS   | DATE      |                                      |        |                    |              |
| DRAWN T.Au  | 7/27/2025 |                                      |        |                    |              |
| ENG M. Hart | 7/27/2025 | TITLE BGA256T1.0C-ISO ISOLATED DUMMY |        |                    |              |
| MFG         |           |                                      |        |                    |              |
| QA          |           | SCALE 5:1                            | SIZE A | DRAWING NO. 511600 | REV A        |
| CUST        |           |                                      |        |                    |              |
| REVISED     |           | DO NOT SCALE DRAWING                 |        |                    |              |
|             |           |                                      |        |                    | SHEET 1 OF 3 |

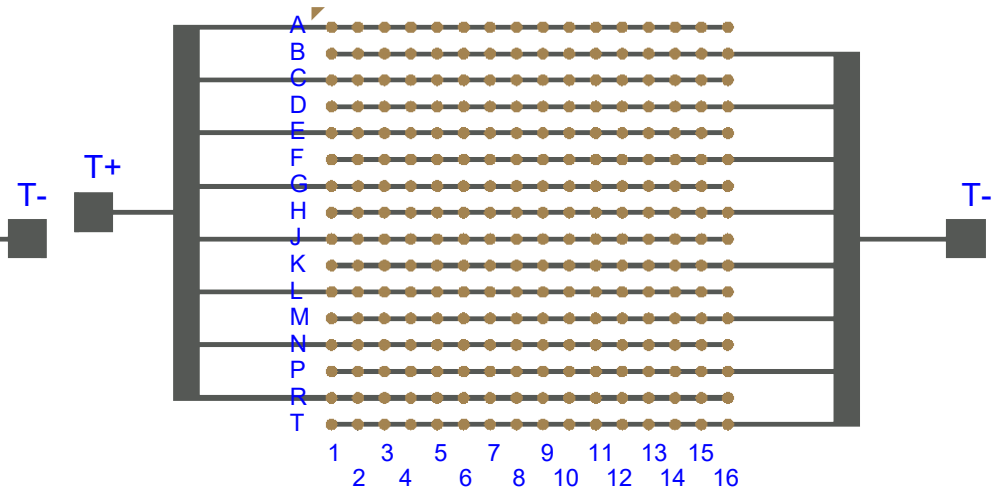
## BALL VIEW



## BOTTOM SIDE (TOP X-RAY VIEW)



## S.I.R TEST BOARD



## AFTER MOUNTING

### Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER: 0.381 (15 MIL).
- 3) PCB TRACING LINE WIDTH 0.20mm (8 MIL).
- 4) NSMD PAD OPENING 0.50mm (20 MIL).

**TopLine®**

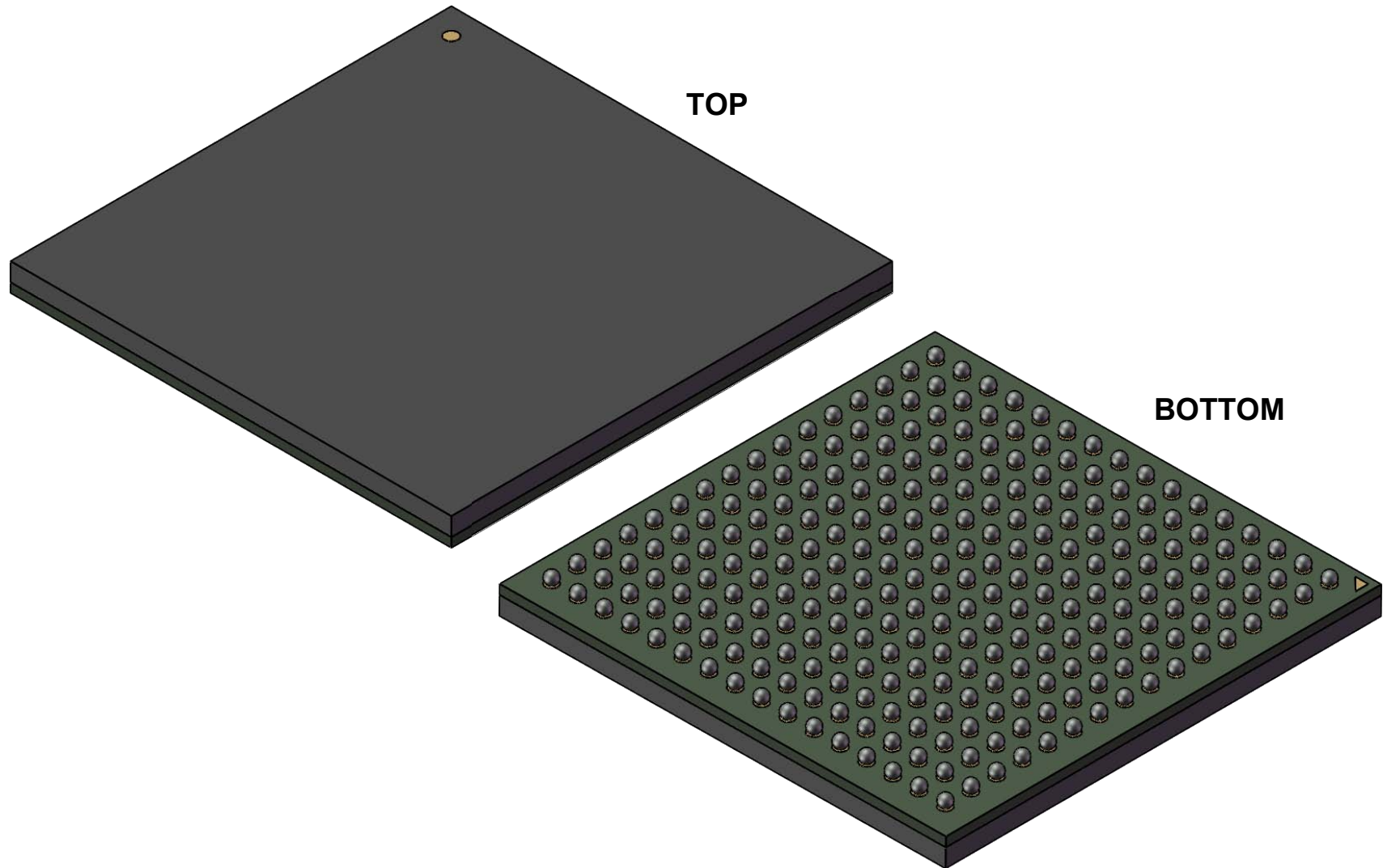
TITLE BGA256T1.0C-ISO  
ISOLATED DUMMY

|                |           |                       |          |
|----------------|-----------|-----------------------|----------|
| SCALE<br>3.5:1 | SIZE<br>A | DRAWING NO.<br>511600 | REV<br>A |
|----------------|-----------|-----------------------|----------|

DO NOT SCALE DRAWING

SHEET 2 OF 3

# MODEL



TOP

BOTTOM

**TopLine®**

TITLE BGA256T1.0C-ISO  
ISOLATED DUMMY

|                |           |                       |          |
|----------------|-----------|-----------------------|----------|
| SCALE<br>3.5:1 | SIZE<br>A | DRAWING NO.<br>511600 | REV<br>A |
|----------------|-----------|-----------------------|----------|

DO NOT SCALE DRAWING

SHEET 3 OF 3